Place Block Diagram here (if appropriate) or delete this text box.
If using a block diagram from another tool, save the picture as a .bmp file.
Then, use menu Place|Drawing Tools|Graphic to insert the .bmp file on the schematic.
Assembly Note
ZZ2
These assemblies are ESD sensitive. ESD precautions shall be observed.

Assembly Note
ZZ3
These assemblies must be clean and free from flux and all contaminants. Use of no-clean flux is not acceptable.

Assembly Note
ZZ4
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
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